ABSOLUTE MAXIMUM RATINGS

V _{DD} to GND	0.3V to +6V
FANOUT to GND	
FORCEON, HYST, FANON to GND	0.3V to (V _{DD} + 0.3V)
WARN, OT to GND	0.3V to +6V
FANOUT Continuous Current	400mA
All Other Pins	±20mA

Continuous Power Dissipation ($T_A = +70^{\circ}C$)

8-Pin SO (derate 19.6mW/°C above +70°C)1568mW
Operating Temperature Range40°C to +125°C
Junction (storage) Temperature Range65°C to +150°C
Lead Temperature (soldering, 10s)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{DD} = +2.7V \text{ to } +5.5V, T_A = -40^{\circ}\text{C} \text{ to } +125^{\circ}\text{C}.$ Typical values are at $V_{DD} = +3.3V$ and $T_A = +25^{\circ}\text{C}$, unless otherwise noted.) (Note 1)

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS	
Supply Voltage	V _{DD} pin	2.7		5.5	V	
Supply Current	No load		65	200	μΑ	
FANOUT Drive Voltage	FANOUT pin			26	V	
FANOUT Output Current Capability	VFANOUT < 0.8V	250			mA	
	$V_{\overline{FANOUT}} < 0.6V, T_A \le T_{TH} + 10^{\circ}C, V_{CC} \ge +3.3V$	250				
FANOUT Leakage Current	$V \overline{FANOUT} = 26V, T_A = +60^{\circ}C$		3		μΑ	
FANOUT Threshold, T _{TH}	MAX6665ASA40		40		°C	
	MAX6665ASA45		45			
	MAX6665ASA50		50			
	MAX6665ASA55		55			
	MAX6665ASA60		60			
	MAX6665ASA65		65			
	MAX6665ASA70		70			
FANOUT Threshold Error		-3	±1	+3	°C	
FANOUT Hysteresis	HYST is unconnected		1		°C	
	HYST ≤ 0.3V _{DD}		4			
	HYST ≥ 0.7V _{DD}		8			
WARN Threshold	Relative to FANOUT temperature threshold		+15		°C	
OT Threshold	Relative to FANOUT temperature threshold		+30		°C	
WARN and OT Hysteresis			2		°C	
FANON Output High Voltage	I _{FANON} = 0.5mA source	2.0			V	
FANON Output Low Voltage	I _{FANON} = 0.5mA sink			0.7	V	
WARN and OT Output Voltage Low	$I_{WARN} = 1.2mA \text{ or } I_{OT} = 1.2mA \text{ sink}$			0.3	V	
	$I_{WARN} = 20 \text{mA or } I_{\overline{OT}} = 20 \text{mA sink}$		0.5			
Open-Drain Leakage Current	$V_{\overline{WARN}} = 5.5V \text{ or } V_{\overline{OT}} = 5.5V$		0.1		μΑ	
Input Low Voltage	FORCEON and HYST pins			0.3V _{DD}	V	
Input High Voltage	FORCEON and HYST pins	0.7V _{DD}			V	
	FORCEON connected to V _{DD} or GND	-1		+1	μΑ	
Input Current	HYST connected to V _{DD} or GND	-15		+15		

Note 1: Specifications over temperature are guaranteed by design. Parts are 100% production tested at 10°C below the temperature threshold.

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Fan Controller/Driver with Factory-Programmed Temperature Thresholds

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 $(V_{DD} = +3.3V, unless otherwise noted.)$





FANOUT CURRENT = 250mA

FANOUT VOLTAGE vs. SUPPLY VOLTAGE



TEMPERATURE THRESHOLD DISTRIBUTION

Typical Operating Characteristics



Pin Description

PIN	NAME	FUNCTION		
1	GND	Ground		
2	FORCEON	Force Fan On Input. Set FORCEON low to force the fan switch on. Set FORCEON high for normal operation.		
3	HYST	Three-State Hysteresis Input. Connect HYST to V _{DD} for 8°C, GND for 4°C, and leave HYST unconnected for 1°C hysteresis.		
4	FANON	Fan-On Indicator Output. Push-pull output. FANON is high when the fan switch is on. FANON is low when the fan switch is off.		
5	ŌŢ	Overtemperature Output. Active-low when the temperature is 30°C above the fan threshold. Open- drain output, requires resistive pullup.		
6	WARN	Overtemperature Warning Output. Active-low when the temperature is 15°C above the fan threshold. Open-drain output, requires resistive pullup.		
7	V _{DD}	Supply Voltage. Bypass with a $1\mu F$ capacitor to GND as close to V_{DD} pin as possible.		
8	FANOUT	Fan-Switch (Driver) Output. Connect to the low side of a fan.		
Exposed Paddle	GND	Ground		

Detailed Description

The MAX6665 is a simple fan controller/driver that turns on the internal power transistor when its die temperature exceeds a factory-set threshold. By connecting a small (typically 5V to 12V, 100mA to 250mA) cooling fan to FANOUT, a simple on/off fan-control system is created. FANOUT drives the fan's low side. The fan's positive supply pin should be connected to its normal power-supply voltage (up to 24V nominal).

To turn the fan on when the MAX6665's die temperature is less than the threshold voltage, drive FORCEON low. This overrides the internal control circuitry and allows an external device to activate the fan. FANON is an active-high push-pull logic output that goes high when the fan is turned on, either when temperature exceeds the threshold or the fan is forced on.

WARN is an active-low, open-drain digital output that indicates the MAX6665's die temperature exceeds 15°C above the fan trip threshold. WARN output serves as a warning that the system temperature has continued to rise well above the fan activation temperature. OT is an active-low open-drain digital output that indicates the MAX6665's die temperature exceeds 30°C above the fan trip threshold. It serves as a thermal shutdown output to the system in case of excessive temperature rise. Figure 1 shows a typical application circuit for a high-reliability, fail-safe temperature monitor.

Applications Information

Thermal Considerations and Hysteresis The temperature comparator has hysteresis to prevent small temperature changes near the threshold temperature from causing the fan to turn on and off repeatedly over short periods of time. The FANOUT pin goes active and powers the fan when the MAX6665's die temperature exceeds the factory-programmed trip temperature. As the cooling fan operates, the circuit board temperature should decrease, which in turn causes the MAX6665's die temperature to decrease. When the die temperature is equal to the trip threshold minus the hysteresis, the FANOUT pin turns the fan off, removing power from the fan. The HYST pin sets the amount of hysteresis to 1°C, 4°C, or 8°C by letting the pin float or connecting to GND or VDD, respectively. This allows the amount of hysteresis to be matched to the cooling and noise requirements of the system.

Hysteresis is also affected by self-heating of the MAX6665's die. The fan current flowing through the onchip power transistor causes the die temperature to increase. For example, assume the MAX6665 controls a 125mA fan. When the fan is operating, the voltage drop across the output transistor is typically under 250mV. At 250mV, the power dissipation is 31.25mW. The thermal resistance of the MAX6665 package (with EP soldered) is 51°C/W, so the die temperature

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Figure 1. High-Reliability, Fail-Safe Fan Controller and Temperature Monitor

increases by a maximum of:

51°C/W x 0.03125W = 1.59°C

Therefore, the effective hysteresis is about 1.59°C higher than the hysteresis selected by the HYST pin. For example, setting the HYST pin for 8°C of hysteresis results in an effective hysteresis of about 9.6°C.

A larger fan with a power-supply current of 250mA causes a maximum voltage drop of 0.6V at the output pin. This results in 150mW power dissipation and the die temperature increases by:

$$51^{\circ}C/W \times 0.150W = 7.65^{\circ}C$$

If the HYST pin has been set for 8°C of hysteresis, the total effective hysteresis will be about 15.7°C.

Using fans with somewhat higher operating current than 250mA results in higher voltage across the output transistor. The increased power dissipation caused by the higher current and voltage levels will increase selfheating, thereby increasing the effective hysteresis. When using higher-power fans, be sure that the MAX6665's power dissipation does not cause so much self-heating that the MAX6665 stays on constantly.

Locating the MAX6665

The location of the MAX6665 in the system affects its operation. Because the fan is turned on and off based on the MAX6665's die temperature, place the MAX6665 close to major heat-generating components in the system—a high-speed CPU or a power device, for example. A higher supply voltage reduces the FANOUT voltage, which reduces the self-heating effects.

The die temperature of the MAX6665 tracks the temperature of its leads and the EP. If it is soldered to a PC board, it quickly reaches the temperature of the traces in that section of the circuit board. Air temperature affects the die temperature. Since the plastic package does not conduct heat as well as the leads, the effect of air temperature is much less than that of lead temperature.

Layout Issues

The MAX6665's GND pin is ground return for the fan driver and the device. Large fan current induces noise (ground bounce) to the MAX6665. Bypass V_{DD} to GND with a 1µF tantalum capacitor located as close to the MAX6665 as possible. For long V_{DD} and GND lines, an additional bypass capacitor may be needed. The bypass capacitor reduces GND noise. The EP is internally connected to the GND pin. Solder the EP to the ground plane for better electrical and thermal performance.



MAX6665

Chip Information

WAX6665

TRANSISTOR COUNT: 1543 MOS 119 BIPOLAR

PROCESS: BICMOS

Package Information



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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